

**Field-induced charged-device model  
test method for electrostatic  
discharge withstand thresholds  
of microelectronic components**

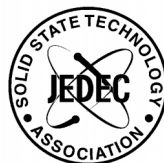
**PUBLICLY AVAILABLE SPECIFICATION**

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INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION



Reference number  
**IEC/PAS 62162**

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# JEDEC STANDARD

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## Test Method C101

### Field-Induced Charged-Device Model Test Method for Electrostatic Discharge Withstand Thresholds of Microelectronic Components

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## JESD22-C101

MAY 1995

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ELECTRONIC INDUSTRIES ASSOCIATION  
ENGINEERING DEPARTMENT





## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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## FIELD-INDUCED CHARGED-DEVICE MODEL TEST METHOD FOR ELECTROSTATIC DISCHARGE WITHSTAND THRESHOLDS OF MICROELECTRONIC COMPONENTS

### FOREWORD

A PAS is a technical specification not fulfilling the requirements for a standard, but made available to the public and established in an organization operating under given procedures.

IEC-PAS 62162 was submitted by JEDEC and has been processed by IEC technical committee 47: Semiconductor devices.

The text of this PAS is based on the following document:

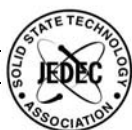
This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document:

Draft PAS	Report on voting
47/1462/PAS	47/1495/RVD

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## TEST METHOD C101

### FIELD-INDUCED CHARGED-DEVICE MODEL TEST METHOD FOR ELECTROSTATIC DISCHARGE WITHSTAND THRESHOLDS OF MICROELECTRONIC COMPONENTS

#### 1. PURPOSE

This standard describes a uniform method for establishing charged-device model (CDM) electrostatic discharge (ESD) withstand thresholds.

#### 2. SCOPE

All packaged semiconductor components, thin film circuits, surface acoustic wave (SAW) components, opto-electronic components, hybrid integrated circuits (HICS), and multi-chip modules (MCMs) containing any of these components are to be evaluated according to this standard. The test methods described in this standard may also be used to evaluate components that are shipped as wafers or bare chips. To perform the tests, the components must be assembled into a package similar to that expected in the final application. The package used shall be recorded.

#### 3. REFERENCE DOCUMENT

JEDEC Standard No. 42, "Requirements for Handling Electrostatic-Discharge-Sensitive (ESDS) Devices."